





LED APPROVAL SHEET

Part No: **BC3737A-AUC**

NOTE :

Green Part

MAKER			CUSTOMER	
				
R&D	QA	Sales	Checked	Approved
				

Prepared	Checked	Approved
Rachel Lee	Sky Lin	Kenneth Wu

BC3737A - AUC

SOLIDLITE LED – BC3737 Series

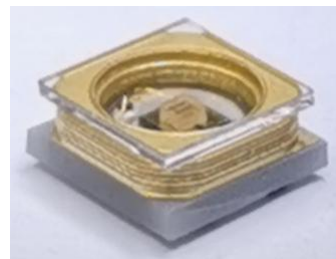


Q'ty : _____ . QA : _____

3737-AUC Series LED Package Product Data Sheet

Features and Applications:

- ◆ Cu Cavity AlN Au-plating Ceramic Package
- ◆ Viewing Angle ($2\theta_{1/2}$): 120 °
- ◆ Solder Pastes for Die Attach
- ◆ Wavelength range: 265~285nm



Product Series

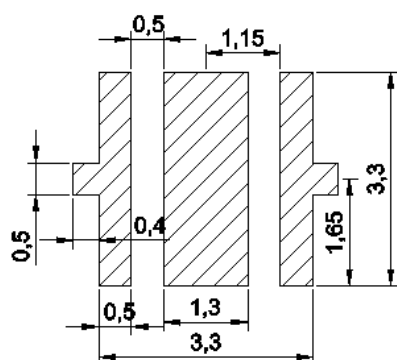
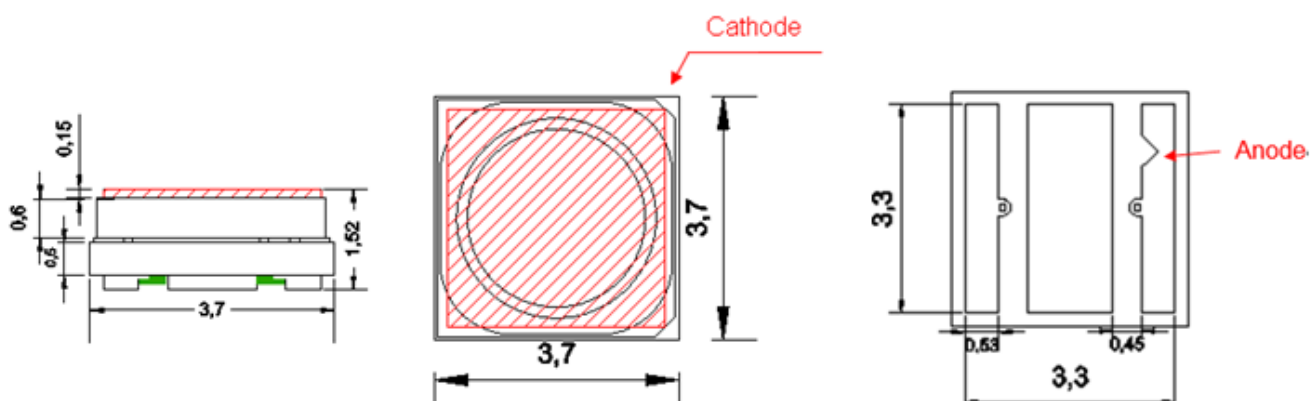
Type	Power Dissipation	Peak Wavelength	Viewing Angle
BC3737A-AUC	1W	265-285nm	120°

Electrical/Optical Characteristics (Ta=25°C)

Parameter	Symbol	Current	Min.	Max.	Units
Radiant Flux	Φ_e	100mA	8	16	mW
Peak Wavelength	WLP	100mA	265	285	nm
Forward Voltage	V_F		6	9	V
Viewing Angle	$2\theta_{1/2}$		120		degrees

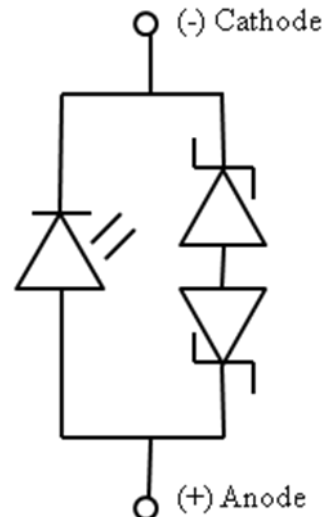
Drawing No.	Rev.	Date	Page
BC3737A-AUC	C	2020/08/11	4/9

Package Dimensions(mm):



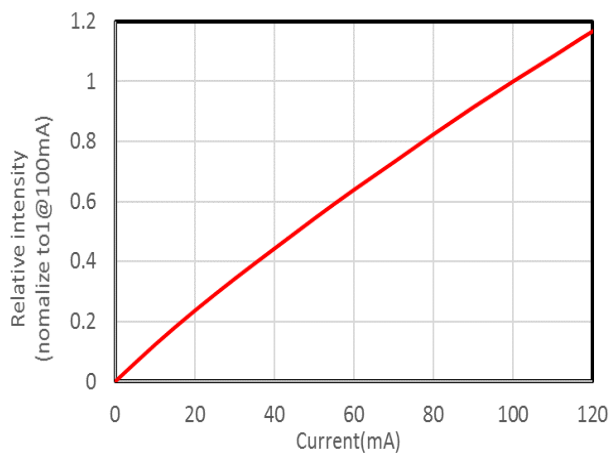
Recommended Solder Pad

Circuit Diagram

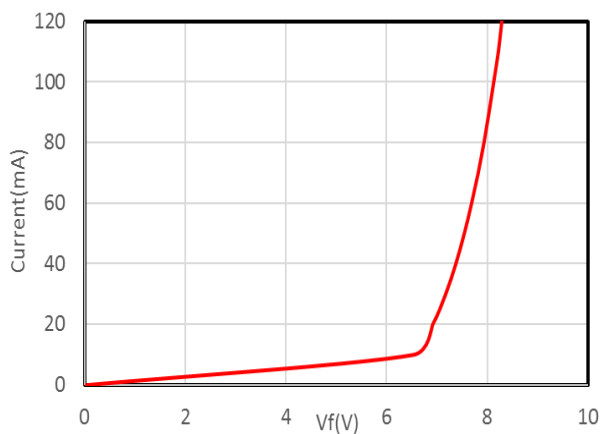


Characteristic Curves:

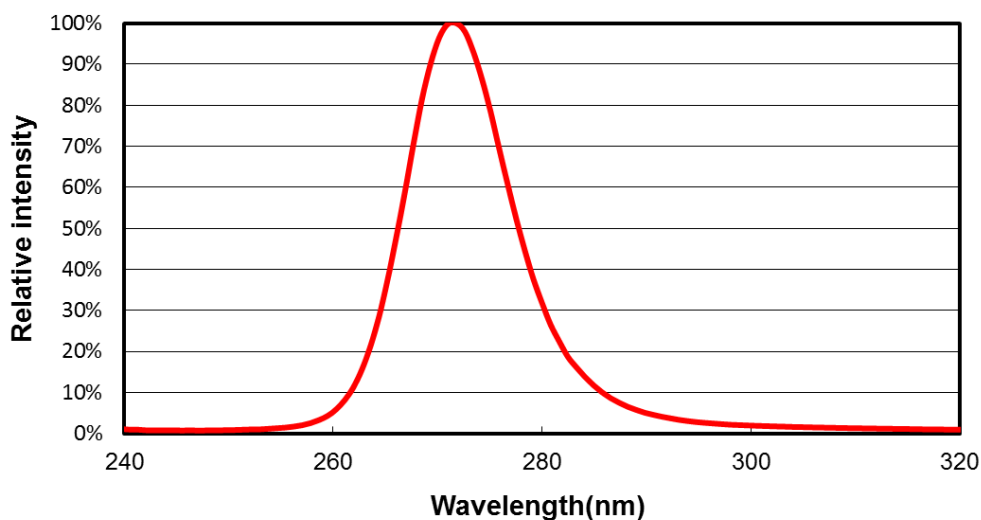
Radiant flux (Φ_e) vs Current(I_F)



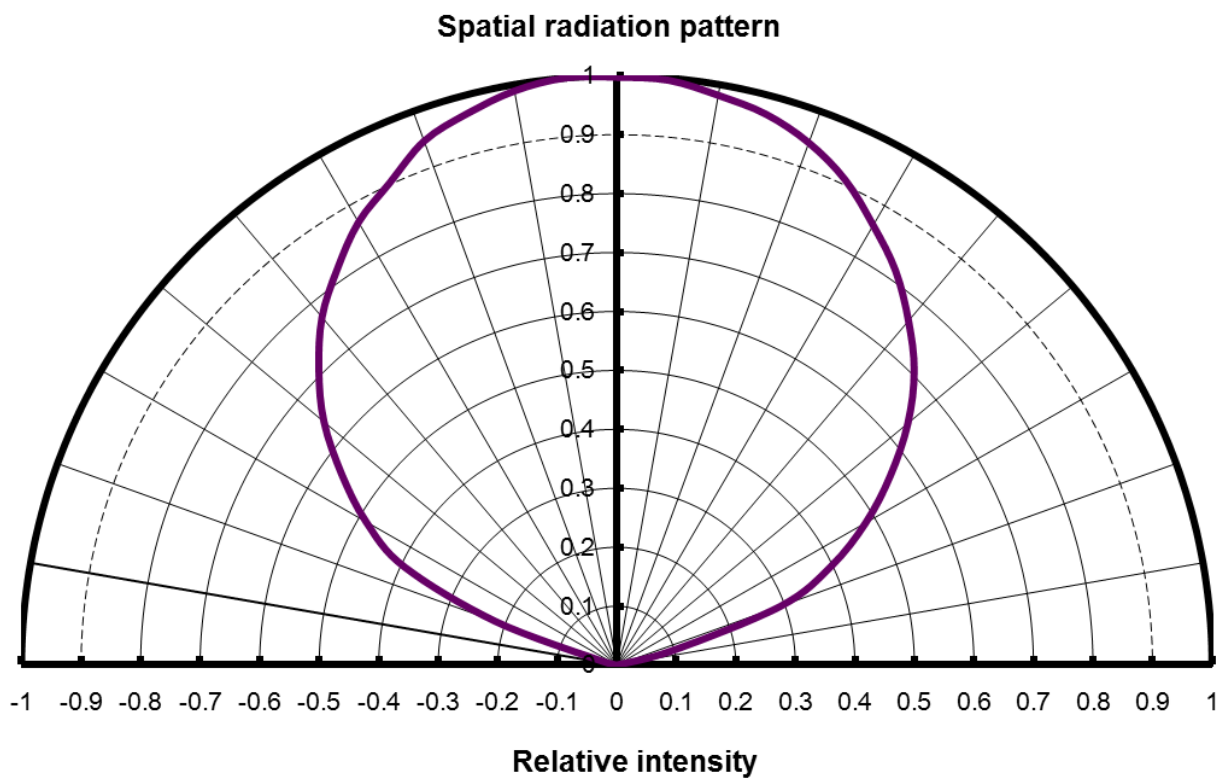
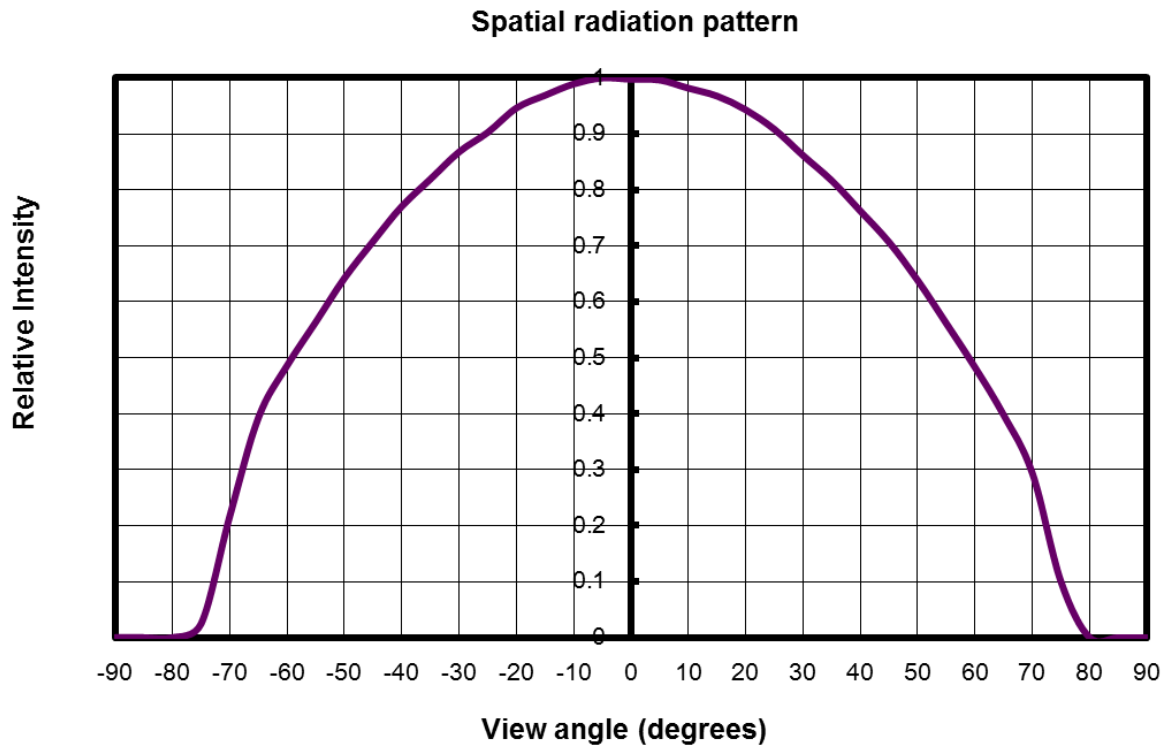
Current(I_F) vs Voltage(V_F)



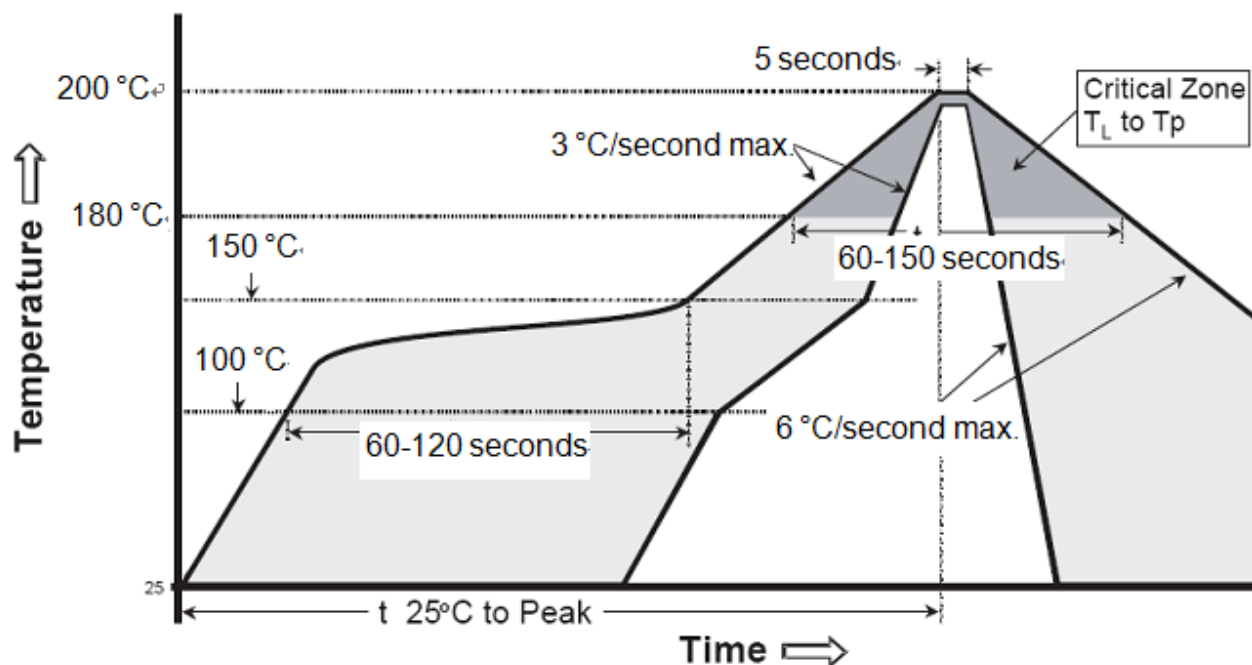
Spectrum Distribution:



Typical Radiation Pattern



Reflow Soldering Profile



Notice

1. This product emits high-intensity ultraviolet light when used. Avoid direct vision or wear ultraviolet goggles to avoid eye damage.
2. This product die attach is solder pastes. The maximum temperature should not exceed 200 °C during reflow soldering.
3. The maximum ambient temperature should be taken into consideration when determining the operating current.
4. In order to avoid absorption of moisture, it is recommended that the products are stored in the dry box (or desiccators) with a desiccants. Alternatively the following environment is recommended: Storage temperature : 5°C~30°C Humidity:60% HR max.
5. If the storage conditions are of high humidity the product should be dried before use. Recommended drying conditions: 12 hours at 60°C±5°C.
6. Devices should be soldered within 7 days after opening the moisture-proof packing. Repack unused product in anti-moisture packing, fold to close any opening and store in a dry place.
7. Devices should not contact with any types of fluid, such as water , oil , organic solvents.... etc. Components should not be mounted on distorted Printed Circuit Boards.
8. Any mechanical force or any excess vibration should be avoid during the cooling process after soldering. Reflow rapidly cooling should be avoided.
9. ESD Precautions Static Electricity and surge damages LEDs. It is recommended that wrist bands or anti-electrostatic gloves be used when handing the LEDs . All devices, equipment and machinery should be properly grounded.
10. This product must be driven by constant power supplier.
11. The appearance and specifications of devices may be modified for improvement without notice.